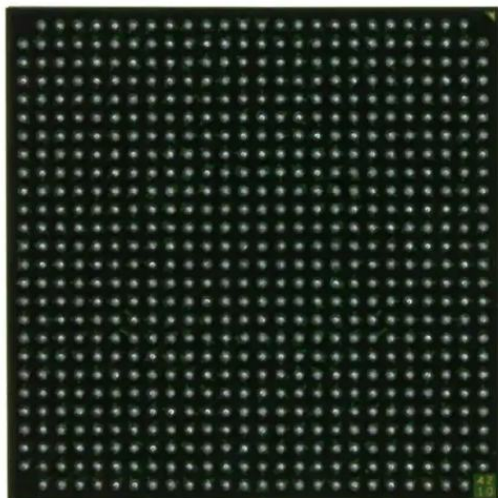




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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	1232
Number of Logic Elements/Cells	11088
Total RAM Bits	811008
Number of I/O	396
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	672-BBGA, FCBGA
Supplier Device Package	672-FCBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp7-6ffg672i



Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Introduction and Overview

DS083 (v5.0) June 21, 2011

Product Specification

Summary of Virtex-II Pro™ / Virtex-II Pro X Features

- High-Performance Platform FPGA Solution, Including
 - Up to twenty RocketIO™ or RocketIO X embedded Multi-Gigabit Transceivers (MGTS)
 - Up to two IBM PowerPC™ RISC processor blocks
- Based on Virtex-II™ Platform FPGA Technology
 - Flexible logic resources
 - SRAM-based in-system configuration
 - Active Interconnect technology
- SelectRAM™+ memory hierarchy
- Dedicated 18-bit x 18-bit multiplier blocks
- High-performance clock management circuitry
- SelectIO™-Ultra technology
- XCITE Digitally Controlled Impedance (DCI) I/O

Virtex-II Pro / Virtex-II Pro X family members and resources are shown in [Table 1](#).

Table 1: Virtex-II Pro / Virtex-II Pro X FPGA Family Members

Device ⁽¹⁾	RocketIO Transceiver Blocks	PowerPC Processor Blocks	Logic Cells ⁽²⁾	CLB (1 = 4 slices = max 128 bits)		18 X 18 Bit Multiplier Blocks	Block SelectRAM+		DCMs	Maximum User I/O Pads
				Slices	Max Distr RAM (Kb)		18 Kb Blocks	Max Block RAM (Kb)		
XC2VP2	4	0	3,168	1,408	44	12	12	216	4	204
XC2VP4	4	1	6,768	3,008	94	28	28	504	4	348
XC2VP7	8	1	11,088	4,928	154	44	44	792	4	396
XC2VP20	8	2	20,880	9,280	290	88	88	1,584	8	564
XC2VPX20	8 ⁽⁴⁾	1	22,032	9,792	306	88	88	1,584	8	552
XC2VP30	8	2	30,816	13,696	428	136	136	2,448	8	644
XC2VP40	0 ⁽³⁾ , 8, or 12	2	43,632	19,392	606	192	192	3,456	8	804
XC2VP50	0 ⁽³⁾ or 16	2	53,136	23,616	738	232	232	4,176	8	852
XC2VP70	16 or 20	2	74,448	33,088	1,034	328	328	5,904	8	996
XC2VPX70	20 ⁽⁴⁾	2	74,448	33,088	1,034	308	308	5,544	8	992
XC2VP100	0 ⁽³⁾ or 20	2	99,216	44,096	1,378	444	444	7,992	12	1,164

Notes:

- 7 speed grade devices are not available in Industrial grade.
- Logic Cell ≈ (1) 4-input LUT + (1)FF + Carry Logic
- These devices can be ordered in a configuration without RocketIO transceivers. See [Table 3](#) for package configurations.
- Virtex-II Pro X devices equipped with RocketIO X transceiver cores.

RocketIO X Transceiver Features (XC2VPX20 and XC2VPX70 Only)

- Variable-Speed Full-Duplex Transceiver (XC2VPX20) Allowing 2.488 Gb/s to 6.25 Gb/s Baud Transfer Rates.
 - Includes specific baud rates used by various standards, as listed in [Table 4, Module 2](#).
- Fixed-Speed Full-Duplex Transceiver (XC2VPX70) Operating at 4.25 Gb/s Baud Transfer Rate.
- Eight or Twenty Transceiver Modules on an FPGA, Depending upon Device
- Monolithic Clock Synthesis and Clock Recovery
 - Eliminates the need for external components
- Automatic Lock-to-Reference Function
- Programmable Serial Output Differential Swing
 - 200 mV to 1600 mV, peak-peak
 - Allows compatibility with other serial system voltage levels
- Programmable Pre-emphasis Levels 0 to 500%
- Telecom/Datacom Support Modes
 - "x8" and "x10" clocking/data paths
 - 64B/66B clocking support

Table 24: RocketIO X Receiver Switching Characteristics⁽¹⁾

Description	Symbol	Conditions	Min	Typ	Max	Units
Receive total jitter tolerance using default equalization and PRBS-15 pattern	T_{JTOL}	2.488 Gb/s		0.80	0.65	UI ⁽²⁾
		3.125 Gb/s		0.80	0.65	UI
		4.25 Gb/s		0.80	0.65	UI
		6.25 Gb/s		0.80	0.65	UI
Receive random jitter tolerance	T_{RJTO}	2.488 Gb/s		0.30		UI
		3.125 Gb/s		0.30		UI
		4.25 Gb/s		0.30		UI
		6.25 Gb/s		0.30		UI
Receive sinusoidal jitter tolerance measured at 70 MHz	T_{SJTO}	2.488 Gb/s		0.30	0.15	UI
		3.125 Gb/s		0.30	0.15	UI
		4.25 Gb/s		0.30	0.15	UI
		6.25 Gb/s		0.30	0.15	UI
Receive deterministic jitter tolerance	T_{DJTO}	2.488 Gb/s		0.55	0.45	UI
		3.125 Gb/s		0.55	0.45	UI
		4.25 Gb/s		0.55	0.45	UI
		6.25 Gb/s		0.50	0.45	UI
Receive latency ⁽³⁾	T_{RXLAT}			25	34 ⁽⁴⁾	RXUSRCLK cycles
RXUSRCLK duty cycle	T_{RXDC}		45	50	55	%
RXUSRCLK2 duty cycle	T_{RX2DC}		45	50	55	%
Differential receive input sensitivity	V_{EYE}			120	250	mV

Notes:

1. The XC2VPX70 operates at a fixed 4.25 Gb/s baud rate.
2. UI = Unit Interval
3. Receive latency delay RXP/RXN to RXDATA. Refer to [RocketIO X Transceiver User Guide](#) for more information on calculating latency.
4. This maximum may occur when certain conditions are present and clock correction and channel bonding are enabled. If these functions are both disabled, the maximum will be near the typical values.

Table 26: RocketIO X Transmitter Switching Characteristics⁽¹⁾

Description	Symbol	Conditions	BREFCLK Frequency	Min	Typ	Max	Units
Serial data rate	F _{GTX}			2.488		6.25	Gb/s
Serial data output total jitter (p-p) ⁽³⁾	T _{TJ}	2.488 Gb/s			0.15	0.20	UI ⁽²⁾
		3.125 Gb/s			0.14	0.19	UI
		4.25 Gb/s			0.39	0.48	UI
		6.25 Gb/s			0.42	0.54	UI
Serial data output deterministic jitter (p-p) ⁽³⁾	T _{DJ}	2.488 Gb/s	155.52 MHz		0.03	0.17	UI
		3.125 Gb/s	156.25 MHz		0.03	0.17	UI
		4.25 Gb/s	212.5 MHz		0.14	0.26	UI
		6.25 Gb/s	312.5 MHz		0.17	0.35	UI
Serial data output random jitter (p-p) ^(3,4)	T _{RJ}	2.488 Gb/s	155.52 MHz		0.12	0.18	UI
		3.125 Gb/s	156.25 MHz		0.12	0.20	UI
		4.25 Gb/s	212.5 MHz		0.25	0.39	UI
		6.25 Gb/s	312.5 MHz		0.25	0.39	UI
TX rise time	T _{RTX}	20% – 80% @ 2.500 Gb/s			60		ps
TX fall time	T _{FTX}				60		ps
Transmit latency ⁽⁵⁾	T _{TXLAT}				14	19	TXUSR CLK cycles
TXUSRCLK duty cycle	T _{TXDC}			45	50	55	%
TXUSRCLK2 duty cycle	T _{TX2DC}			45	50	55	%

Notes:

1. The XC2VPX70 operates at a fixed 4.25 Gb/s baud rate.
2. UI = Unit Interval
3. Total Jitter T_{TJ} = T_{DJ} + T_{RJ}
4. T_{RJ} specifications are *wideband* and include low-frequency jitter components (also referred to as *wander*). T_{RJ} specified is peak-to-peak, estimated at BER=10⁻¹² using the Bathtub Method.
5. Transmit latency delay TXDATA to TXP/TXN. Refer to [RocketIO X Transceiver User Guide](#) for more information on calculating latency.

Multiplier Switching Characteristics

Table 45: Multiplier Switching Characteristics

		Speed Grade			
Description	Symbol	-7	-6	-5	Units
Propagation Delay to Output Pin					
Input to Pin35	T _{MULT_P35}	4.08	4.64	5.19	ns, max
Input to Pin34	T _{MULT_P34}	3.99	4.55	5.09	ns, max
Input to Pin33	T _{MULT_P33}	3.90	4.45	4.99	ns, max
Input to Pin32	T _{MULT_P32}	3.80	4.36	4.88	ns, max
Input to Pin31	T _{MULT_P31}	3.71	4.27	4.78	ns, max
Input to Pin30	T _{MULT_P30}	3.62	4.17	4.67	ns, max
Input to Pin29	T _{MULT_P29}	3.53	4.08	4.57	ns, max
Input to Pin28	T _{MULT_P28}	3.43	3.99	4.46	ns, max
Input to Pin27	T _{MULT_P27}	3.34	3.89	4.36	ns, max
Input to Pin26	T _{MULT_P26}	3.25	3.80	4.26	ns, max
Input to Pin25	T _{MULT_P25}	3.16	3.71	4.15	ns, max
Input to Pin24	T _{MULT_P24}	3.06	3.61	4.05	ns, max
Input to Pin23	T _{MULT_P23}	2.97	3.52	3.94	ns, max
Input to Pin22	T _{MULT_P22}	2.88	3.43	3.84	ns, max
Input to Pin21	T _{MULT_P21}	2.79	3.34	3.73	ns, max
Input to Pin20	T _{MULT_P20}	2.70	3.24	3.63	ns, max
Input to Pin19	T _{MULT_P19}	2.60	3.15	3.53	ns, max
Input to Pin18	T _{MULT_P18}	2.51	3.06	3.42	ns, max
Input to Pin17	T _{MULT_P17}	2.42	2.96	3.32	ns, max
Input to Pin16	T _{MULT_P16}	2.34	2.86	3.21	ns, max
Input to Pin15	T _{MULT_P15}	2.27	2.76	3.09	ns, max
Input to Pin14	T _{MULT_P14}	2.19	2.67	2.98	ns, max
Input to Pin13	T _{MULT_P13}	2.12	2.57	2.87	ns, max
Input to Pin12	T _{MULT_P12}	2.04	2.47	2.76	ns, max
Input to Pin11	T _{MULT_P11}	1.96	2.37	2.65	ns, max
Input to Pin10	T _{MULT_P10}	1.89	2.27	2.54	ns, max
Input to Pin9	T _{MULT_P9}	1.81	2.17	2.43	ns, max
Input to Pin8	T _{MULT_P8}	1.74	2.07	2.32	ns, max
Input to Pin7	T _{MULT_P7}	1.66	1.97	2.21	ns, max
Input to Pin6	T _{MULT_P6}	1.59	1.87	2.09	ns, max
Input to Pin5	T _{MULT_P5}	1.51	1.77	1.98	ns, max
Input to Pin4	T _{MULT_P4}	1.44	1.67	1.87	ns, max
Input to Pin3	T _{MULT_P3}	1.36	1.57	1.76	ns, max
Input to Pin2	T _{MULT_P2}	1.28	1.47	1.65	ns, max
Input to Pin1	T _{MULT_P1}	1.21	1.37	1.54	ns, max
Input to Pin0	T _{MULT_P0}	1.13	1.27	1.43	ns, max

Master/Slave SelectMAP Parameters

Figure 10 is a generic timing diagram for data loading using SelectMAP. For other data loading diagrams, refer to the [Virtex-II Pro Platform FPGA User Guide](#).

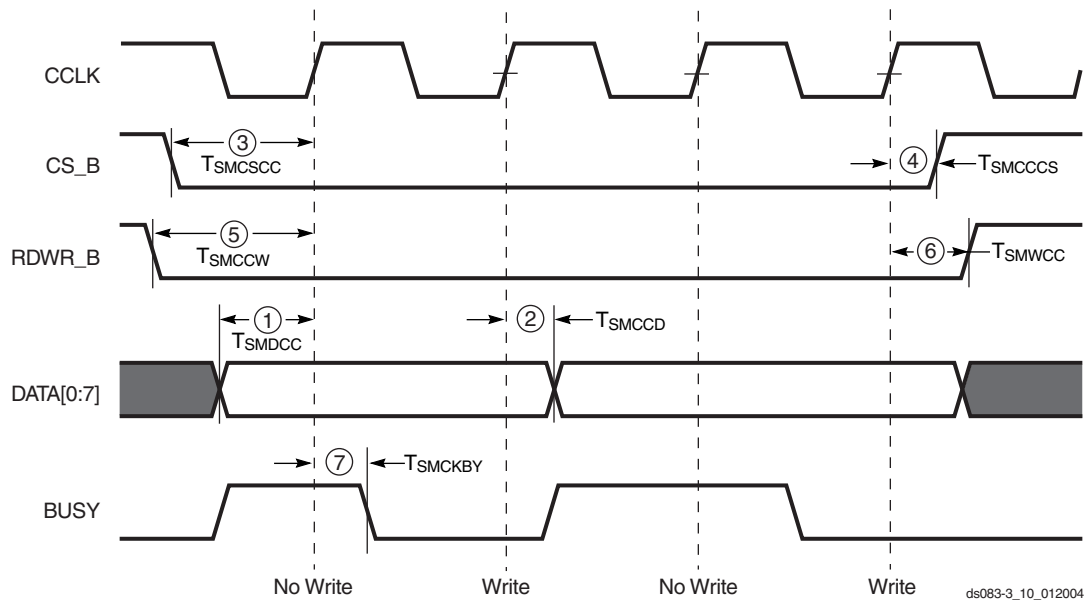


Figure 10: SelectMAP Mode Data Loading Sequence (Generic)

Table 51: SelectMAP Mode Write Timing Characteristics

	Description	Device	Figure References	Symbol	Value	Units
CCLK	DATA[0:7] setup/hold	XC2VP2	1/2	T_{SMDCC}/T_{SMCCD}	5.0/0.0	ns, min
		XC2VP4			5.0/0.0	ns, min
		XC2VP7			5.0/0.0	ns, min
		XC2VP20			5.0/0.0	ns, min
		XC2VPX20			5.0/0.0	ns, min
		XC2VP30			5.0/0.0	ns, min
		XC2VP40			5.0/0.0	ns, min
		XC2VP50			5.0/0.0	ns, min
		XC2VP70			6.0/0.0	ns, min
		XC2VPX70			6.0/0.0	ns, min
		XC2VP100			7.5/0.0	ns, min
	CS_B setup/hold		3/4	T_{SMCSCC}/T_{SMCCCS}	7.0/0.0	ns, min
	RDWR_B setup/hold		5/6	T_{SMCCW}/T_{SMWCC}	7.0/0.0	ns, min
	BUSY propagation delay		7	T_{SMCKBY}	12.0	ns, max
	Maximum start-up frequency			$F_{CC_STARTUP}$	50	MHz, max
	Maximum frequency			$F_{CC_SELECTMAP}$	50	MHz, max
	Maximum frequency with no handshake			F_{CCNH}	50	MHz, max

Virtex-II Pro Pin-to-Pin Output Parameter Guidelines

All devices are 100% functionally tested. Listed below are representative values for typical pin locations and normal clock loading. Values are expressed in nanoseconds unless otherwise noted.

Global Clock Input to Output Delay for LVCMOS25, 12 mA, Fast Slew Rate, With DCM

Table 53: Global Clock Input to Output Delay for LVCMOS25, 12 mA, Fast Slew Rate, With DCM

			Speed Grade			
Description	Symbol	Device	-7	-6	-5	Units
LVC MOS25 Global Clock Input to Output Delay using Output Flip-flop, 12 mA, Fast Slew Rate, <i>with</i> DCM. For data <i>output</i> with different standards, adjust the delays with the values shown in IOB Output Switching Characteristics Standard Adjustments , page 28.						
Global Clock and OFF with DCM	T _{ICKOFFDCM}	XC2VP2	1.55	1.59	1.62	ns
		XC2VP4	1.58	1.61	1.65	ns
		XC2VP7	1.63	1.68	1.72	ns
		XC2VP20	1.68	1.74	1.79	ns
		XC2VPX20	1.68	1.74	1.79	ns
		XC2VP30	1.68	1.75	1.80	ns
		XC2VP40	1.71	1.86	1.92	ns
		XC2VP50	1.80	2.00	2.07	ns
		XC2VP70	1.87	2.07	2.24	ns
		XC2VPX70	1.87	2.07	2.24	ns
		XC2VP100	N/A	2.38	2.45	ns

Notes:

1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. Output timing is measured at 50% V_{CC} threshold with test setup shown in [Figure 6](#). For other I/O standards, see [Table 40](#).
3. DCM output jitter is already included in the timing calculation.

Table 6: FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
1	IO_L07P_1	F14			
1	IO_L06N_1	C15			
1	IO_L06P_1	D15			
1	IO_L05_1/No_Pair	E15			
1	IO_L03N_1/VREF_1	C16			
1	IO_L03P_1	D16			
1	IO_L02N_1	E16			
1	IO_L02P_1	E17			
1	IO_L01N_1/VRP_1	D17			
1	IO_L01P_1/VRN_1	D18			
2	IO_L01N_2/VRP_2	C21			
2	IO_L01P_2/VRN_2	C22			
2	IO_L02N_2	D21			
2	IO_L02P_2	D22			
2	IO_L03N_2	E19			
2	IO_L03P_2	E20			
2	IO_L04N_2/VREF_2	E21			
2	IO_L04P_2	E22			
2	IO_L06N_2	F19			
2	IO_L06P_2	F20			
2	IO_L43N_2	F21	NC		
2	IO_L43P_2	F22	NC		
2	IO_L46N_2/VREF_2	F18	NC		
2	IO_L46P_2	G18	NC		
2	IO_L48N_2	G19	NC		
2	IO_L48P_2	G20	NC		
2	IO_L49N_2	G21	NC		
2	IO_L49P_2	G22	NC		
2	IO_L50N_2	H19	NC		
2	IO_L50P_2	H20	NC		
2	IO_L52N_2/VREF_2	H21	NC		
2	IO_L52P_2	H22	NC		
2	IO_L54N_2	H18	NC		
2	IO_L54P_2	J17	NC		
2	IO_L55N_2	J19	NC		
2	IO_L55P_2	J20	NC		

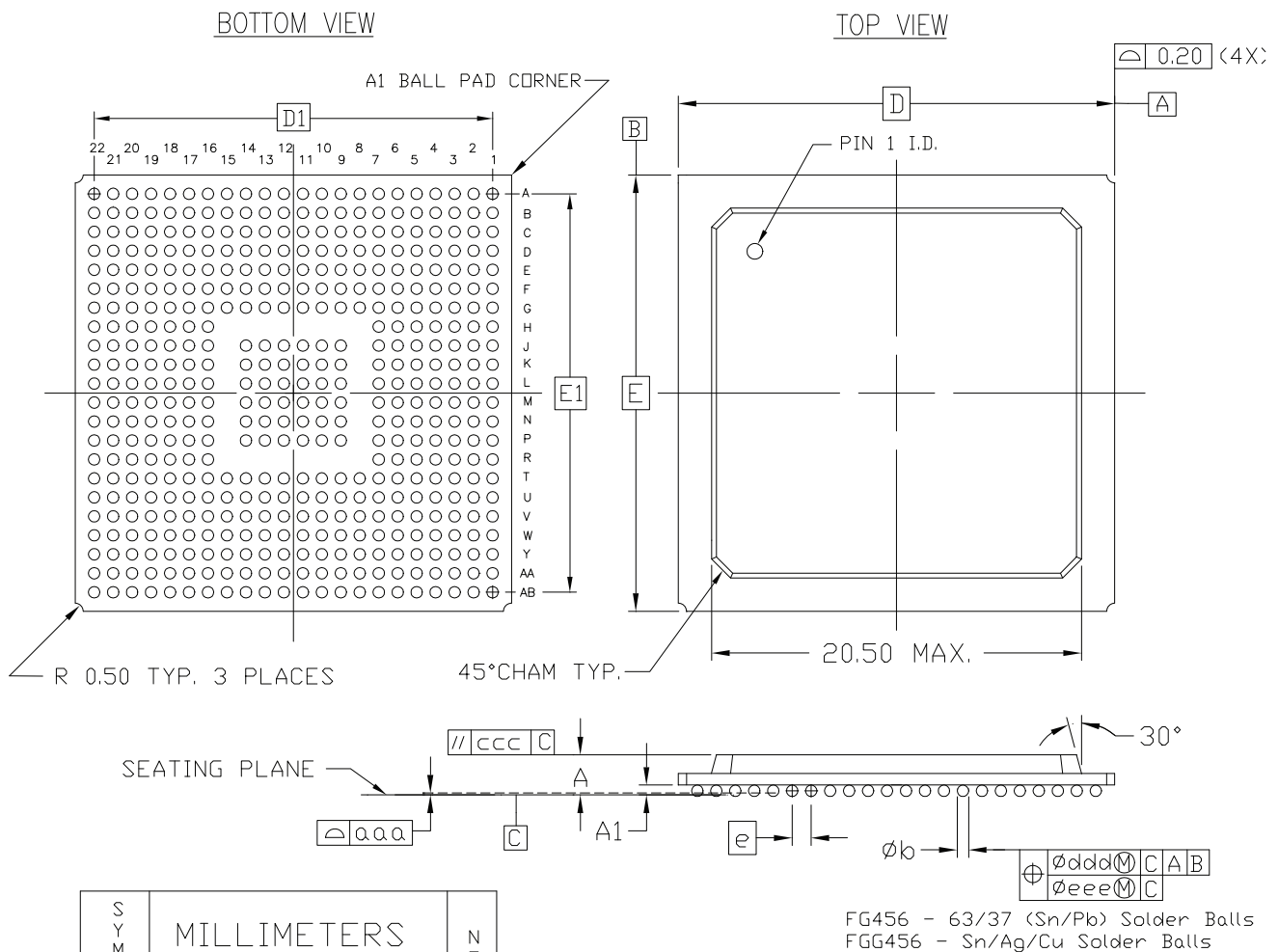
Table 6: FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
6	IO_L06N_6	V1			
6	IO_L43P_6	U4	NC		
6	IO_L43N_6	U3	NC		
6	IO_L45P_6	U2	NC		
6	IO_L45N_6/VREF_6	U1	NC		
6	IO_L47P_6	U5	NC		
6	IO_L47N_6	T5	NC		
6	IO_L48P_6	T4	NC		
6	IO_L48N_6	T3	NC		
6	IO_L49P_6	T2	NC		
6	IO_L49N_6	T1	NC		
6	IO_L51P_6	R4	NC		
6	IO_L51N_6/VREF_6	R3	NC		
6	IO_L53P_6	R2	NC		
6	IO_L53N_6	R1	NC		
6	IO_L54P_6	R5	NC		
6	IO_L54N_6	P6	NC		
6	IO_L55P_6	P4	NC		
6	IO_L55N_6	P3	NC		
6	IO_L57P_6	P2	NC		
6	IO_L57N_6/VREF_6	P1	NC		
6	IO_L59P_6	P5	NC		
6	IO_L59N_6	N5	NC		
6	IO_L60P_6	N4	NC		
6	IO_L60N_6	N3	NC		
6	IO_L85P_6	N2			
6	IO_L85N_6	N1			
6	IO_L87P_6	N6			
6	IO_L87N_6/VREF_6	M6			
6	IO_L89P_6	M5			
6	IO_L89N_6	M4			
6	IO_L90P_6	M3			
6	IO_L90N_6	M2			
7	IO_L90P_7	L2			
7	IO_L90N_7	L3			
7	IO_L88P_7	L4			

Table 6: FG456/FGG456 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
0	VCCO_0	G9			
0	VCCO_0	G11			
0	VCCO_0	G10			
0	VCCO_0	F8			
0	VCCO_0	F7			
1	VCCO_1	G14			
1	VCCO_1	G13			
1	VCCO_1	G12			
1	VCCO_1	F16			
1	VCCO_1	F15			
2	VCCO_2	L16			
2	VCCO_2	K16			
2	VCCO_2	J16			
2	VCCO_2	H17			
2	VCCO_2	G17			
3	VCCO_3	T17			
3	VCCO_3	R17			
3	VCCO_3	P16			
3	VCCO_3	N16			
3	VCCO_3	M16			
4	VCCO_4	U16			
4	VCCO_4	U15			
4	VCCO_4	T14			
4	VCCO_4	T13			
4	VCCO_4	T12			
5	VCCO_5	U8			
5	VCCO_5	U7			
5	VCCO_5	T9			
5	VCCO_5	T11			
5	VCCO_5	T10			
6	VCCO_6	T6			
6	VCCO_6	R6			
6	VCCO_6	P7			
6	VCCO_6	N7			
6	VCCO_6	M7			
7	VCCO_7	L7			

FG456/FGG456 Fine-Pitch BGA Package Specifications (1.00mm pitch)



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	xx	xx	2.60	3
A ₁	0.35	0.50	0.60	
D/E	23.00 BSC			
D ₁ /E ₁	21.00 REF			
e	1.00 BSC			
øb	0.50	0.60	0.70	
aaa	xx	xx	0.20	
ccc	xx	xx	0.35	2
ddd	xx	xx	0.30	
eee	xx	xx	0.10	
M	22			

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. NOMINAL 'A' DIMENSION IS TYPICALLY 2.20mm.
4. CONFORMS TO JEDEC MS-034-AAJ-1 (DEPOPULATED)

Figure 2: FG456/FGG456 Fine-Pitch BGA Package Specifications

Table 7: FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
5	IO_L46N_5	W11			
5	IO_L46P_5	W10			
5	IO_L45N_5/VREF_5	AD9			
5	IO_L45P_5	AC9			
5	IO_L43N_5	AB9			
5	IO_L43P_5	AA9			
5	IO_L39N_5	Y9			
5	IO_L39P_5	W9			
5	IO_L37N_5	AF8			
5	IO_L37P_5	AE8			
5	IO_L09N_5/VREF_5	AB8			
5	IO_L09P_5	AA8			
5	IO_L07N_5/VREF_5	Y8			
5	IO_L07P_5	W8			
5	IO_L06N_5/VRP_5	AD7			
5	IO_L06P_5/VRN_5	AC7			
5	IO_L05_5/No_Pair	AB7			
5	IO_L03N_5/D4	AA7			
5	IO_L03P_5/D5	Y7			
5	IO_L02N_5/D6	AC6			
5	IO_L02P_5/D7	AB6			
5	IO_L01N_5/RDWR_B	AC5			
5	IO_L01P_5/CS_B	AB5			
6	IO_L01P_6/VRN_6	AE1			
6	IO_L01N_6/VRP_6	AD1			
6	IO_L02P_6	AD2			
6	IO_L02N_6	AC3			
6	IO_L03P_6	AC2			
6	IO_L03N_6/VREF_6	AC1			
6	IO_L05P_6	AB4			
6	IO_L05N_6	AA5			
6	IO_L06P_6	AB2			
6	IO_L06N_6	AB1			
6	IO_L23P_6	AA6	NC		

Table 7: FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
N/A	GND	R15			
N/A	GND	R16			
N/A	GND	R24			
N/A	GND	T11			
N/A	GND	T12			
N/A	GND	T13			
N/A	GND	T14			
N/A	GND	T15			
N/A	GND	T16			
N/A	GND	U6			
N/A	GND	U21			
N/A	GND	W4			
N/A	GND	W23			
N/A	GND	AA10			
N/A	GND	AA17			
N/A	GND	AC4			
N/A	GND	AC8			
N/A	GND	AC19			
N/A	GND	AC23			
N/A	GND	AD3			
N/A	GND	AD24			
N/A	GND	AE2			
N/A	GND	AE25			
N/A	GND	AF1			
N/A	GND	AF26			

Notes:

1. See [Table 4](#) for an explanation of the signals available on this pin.

Table 8: FF672 — XC2VP2, XC2VP4, and XC2VP7

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
N/A	VCCINT	U16			
N/A	VCCINT	U18			
N/A	VCCINT	V10			
N/A	VCCINT	V17			
N/A	VCCINT	V18			
N/A	VCCINT	W19			
N/A	VCCAUX	B2			
N/A	VCCAUX	N1			
N/A	VCCAUX	P1			
N/A	VCCAUX	A13			
N/A	VCCAUX	A14			
N/A	VCCAUX	AE2			
N/A	VCCAUX	B25			
N/A	VCCAUX	N26			
N/A	VCCAUX	P26			
N/A	VCCAUX	AE25			
N/A	VCCAUX	AF13			
N/A	VCCAUX	AF14			
N/A	GND	C3			
N/A	GND	D4			
N/A	GND	E5			
N/A	GND	F6			
N/A	GND	G7			
N/A	GND	Y7			
N/A	GND	AA6			
N/A	GND	AB5			
N/A	GND	AC4			
N/A	GND	AD3			
N/A	GND	C24			
N/A	GND	D23			
N/A	GND	E22			
N/A	GND	F21			
N/A	GND	G20			
N/A	GND	K10			
N/A	GND	K12			
N/A	GND	K13			
N/A	GND	K14			

FF1152 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)

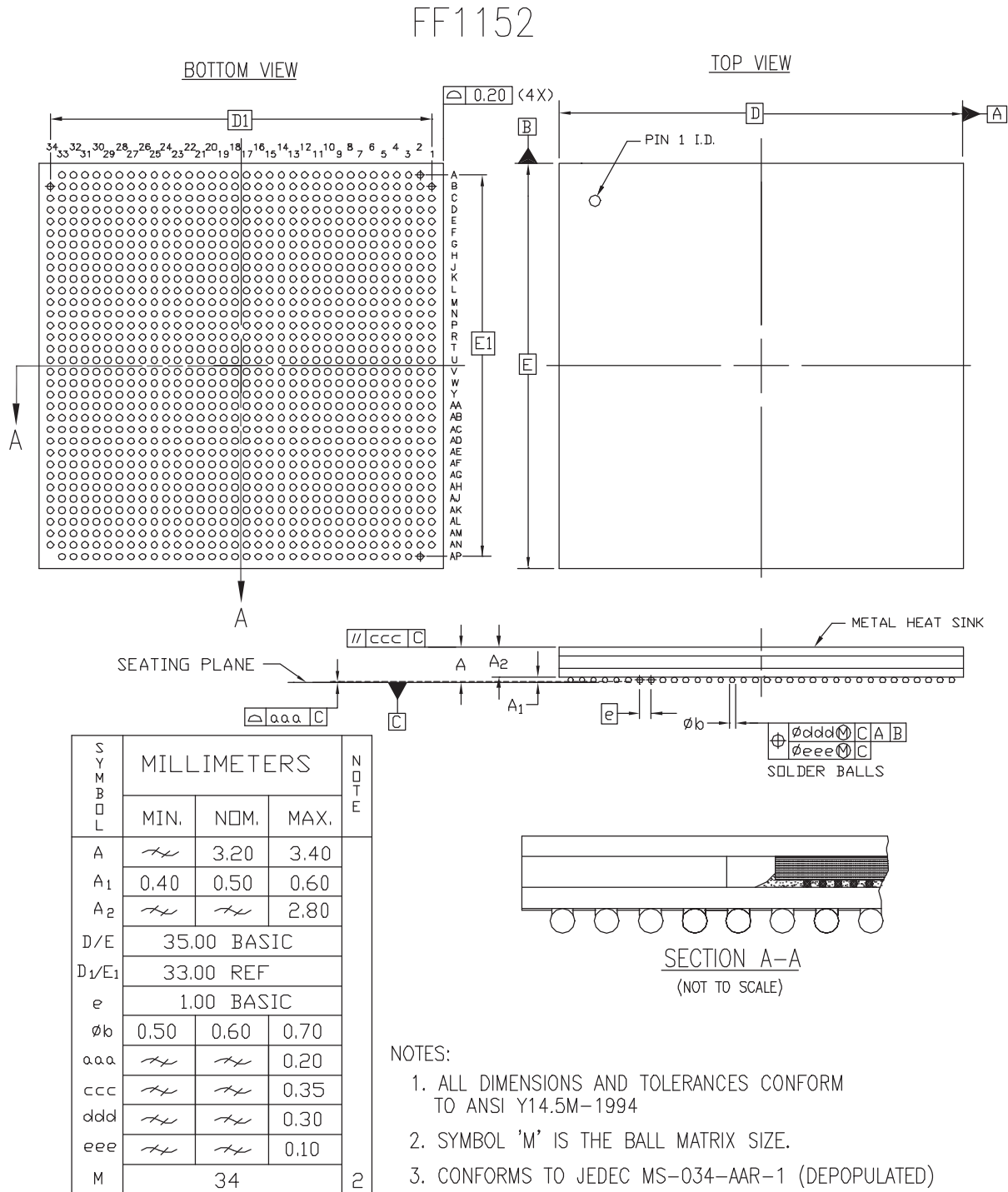


Figure 6: FF1152 Flip-Chip Fine-Pitch BGA Package Specifications

Table 11: FF1148 — XC2VP40 and XC2VP50

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
2	IO_L40P_2	K3		
2	IO_L41N_2	R9		
2	IO_L41P_2	P9		
2	IO_L42N_2	K1		
2	IO_L42P_2	K2		
2	IO_L43N_2	L5		
2	IO_L43P_2	L6		
2	IO_L44N_2	P7		
2	IO_L44P_2	P8		
2	IO_L45N_2	L1		
2	IO_L45P_2	L2		
2	IO_L46N_2/VREF_2	M5		
2	IO_L46P_2	M6		
2	IO_L47N_2	R10		
2	IO_L47P_2	R11		
2	IO_L48N_2	M3		
2	IO_L48P_2	M4		
2	IO_L49N_2	M1		
2	IO_L49P_2	M2		
2	IO_L50N_2	R7		
2	IO_L50P_2	T8		
2	IO_L51N_2	P4		
2	IO_L51P_2	N4		
2	IO_L52N_2/VREF_2	N2		
2	IO_L52P_2	N3		
2	IO_L53N_2	T10		
2	IO_L53P_2	T11		
2	IO_L54N_2	P5		
2	IO_L54P_2	P6		
2	IO_L55N_2	R3		
2	IO_L55P_2	P3		
2	IO_L56N_2	T6		
2	IO_L56P_2	T7		
2	IO_L57N_2	P1		
2	IO_L57P_2	P2		
2	IO_L58N_2/VREF_2	R5		
2	IO_L58P_2	R6		
2	IO_L59N_2	U10		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
3	IO_L90P_3	AA8		
3	IO_L89N_3	Y11		
3	IO_L89P_3	Y12		
3	IO_L88N_3	AA5		
3	IO_L88P_3	AA6		
3	IO_L87N_3/VREF_3	AA3		
3	IO_L87P_3	AA4		
3	IO_L86N_3	Y13		
3	IO_L86P_3	AA13		
3	IO_L85N_3	AB7		
3	IO_L85P_3	AB8		
3	IO_L60N_3	AB5		
3	IO_L60P_3	AB6		
3	IO_L59N_3	AA9		
3	IO_L59P_3	AA10		
3	IO_L58N_3	AB3		
3	IO_L58P_3	AB4		
3	IO_L57N_3/VREF_3	AB1		
3	IO_L57P_3	AB2		
3	IO_L56N_3	AA11		
3	IO_L56P_3	AA12		
3	IO_L55N_3	AC5		
3	IO_L55P_3	AC6		
3	IO_L54N_3	AC1		
3	IO_L54P_3	AC2		
3	IO_L53N_3	AB9		
3	IO_L53P_3	AB10		
3	IO_L52N_3	AC8		
3	IO_L52P_3	AD8		
3	IO_L51N_3/VREF_3	AC4		
3	IO_L51P_3	AD4		
3	IO_L50N_3	AB11		
3	IO_L50P_3	AB12		
3	IO_L49N_3	AD6		
3	IO_L49P_3	AD7		
3	IO_L48N_3	AD2		
3	IO_L48P_3	AD3		
3	IO_L47N_3	AC9		

Table 12: FF1517 — XC2VP50 and XC2VP70

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	TXNPAD23	AW36		
N/A	VTTXPAD23	AV36		
N/A	AVCCAUXTX23	AV35		
N/A	VCCINT	AH28		
N/A	VCCINT	M28		
N/A	VCCINT	AG27		
N/A	VCCINT	N27		
N/A	VCCINT	AF26		
N/A	VCCINT	P26		
N/A	VCCINT	AE25		
N/A	VCCINT	AD25		
N/A	VCCINT	AC25		
N/A	VCCINT	AB25		
N/A	VCCINT	AA25		
N/A	VCCINT	Y25		
N/A	VCCINT	W25		
N/A	VCCINT	V25		
N/A	VCCINT	U25		
N/A	VCCINT	T25		
N/A	VCCINT	R25		
N/A	VCCINT	AE24		
N/A	VCCINT	AD24		
N/A	VCCINT	T24		
N/A	VCCINT	R24		
N/A	VCCINT	AE23		
N/A	VCCINT	R23		
N/A	VCCINT	AE22		
N/A	VCCINT	R22		
N/A	VCCINT	AE21		
N/A	VCCINT	R21		
N/A	VCCINT	AE20		
N/A	VCCINT	R20		
N/A	VCCINT	AE19		
N/A	VCCINT	R19		
N/A	VCCINT	AE18		
N/A	VCCINT	R18		
N/A	VCCINT	AE17		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
0	IO_L49P_0		G26		
0	IO_L50_0/No_Pair		D27		
0	IO_L53_0/No_Pair		D26		
0	IO_L54N_0		K25		
0	IO_L54P_0		L25		
0	IO_L55N_0		G25		
0	IO_L55P_0		H25		
0	IO_L56N_0		E26		
0	IO_L56P_0		E25		
0	IO_L57N_0		C25		
0	IO_L57P_0/VREF_0		C26		
0	IO_L58N_0		L24		
0	IO_L58P_0		M24		
0	IO_L59N_0		J24		
0	IO_L59P_0		K24		
0	IO_L60N_0		G24		
0	IO_L60P_0		H24		
0	IO_L64N_0		E24		
0	IO_L64P_0		F24		
0	IO_L65N_0		D24		
0	IO_L65P_0		C24		
0	IO_L66N_0		M22		
0	IO_L66P_0/VREF_0		M23		
0	IO_L67N_0		K23		
0	IO_L67P_0		L23		
0	IO_L68N_0		J23		
0	IO_L68P_0		H23		
0	IO_L69N_0		E23		
0	IO_L69P_0/VREF_0		F23		
0	IO_L73N_0		C23		
0	IO_L73P_0		D23		
0	IO_L74N_0/GCLK7P		K22		
0	IO_L74P_0/GCLK6S		J22		
0	IO_L75N_0/GCLK5P	BREFCLKN	F22		
0	IO_L75P_0/GCLK4S	BREFCLKP	G22		

Table 13: FF1704 — XC2VP70, XC2VPX70, and XC2VP100

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
7	IO_L09P_7		K36		
7	IO_L09N_7		K35		
7	IO_L08P_7		K38		
7	IO_L08N_7		K37		
7	IO_L07P_7		L33		
7	IO_L07N_7		K34		
7	IO_L84P_7		J41		
7	IO_L84N_7		J42		
7	IO_L83P_7		J39		
7	IO_L83N_7		J38		
7	IO_L82P_7		J36		
7	IO_L82N_7/VREF_7		J37		
7	IO_L81P_7		J35		
7	IO_L81N_7		H36		
7	IO_L80P_7		H41		
7	IO_L80N_7		H40		
7	IO_L79P_7		H38		
7	IO_L79N_7		H39		
7	IO_L78P_7		H37		
7	IO_L78N_7		G38		
7	IO_L77P_7		G42		
7	IO_L77N_7		G41		
7	IO_L76P_7		G39		
7	IO_L76N_7/VREF_7		G40		
7	IO_L75P_7		F41		
7	IO_L75N_7		F42		
7	IO_L74P_7		F40		
7	IO_L74N_7		F39		
7	IO_L73P_7		E41		
7	IO_L73N_7		E42		
7	IO_L06P_7		D41		
7	IO_L06N_7		D42		
7	IO_L05P_7		E40		
7	IO_L05N_7		D40		
7	IO_L04P_7		F36		
7	IO_L04N_7/VREF_7		G37		

Table 14: FF1696 — XC2VP100

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
5	VCCO_5	AL30	
5	VCCO_5	AW29	
5	VCCO_5	AR29	
5	VCCO_5	AJ26	
5	VCCO_5	AW25	
5	VCCO_5	AR25	
5	VCCO_5	AJ25	
5	VCCO_5	AH25	
5	VCCO_5	AJ24	
5	VCCO_5	AH24	
5	VCCO_5	AJ23	
5	VCCO_5	AH23	
5	VCCO_5	AJ22	
5	VCCO_5	AH22	
4	VCCO_4	AJ21	
4	VCCO_4	AH21	
4	VCCO_4	AJ20	
4	VCCO_4	AH20	
4	VCCO_4	AJ19	
4	VCCO_4	AH19	
4	VCCO_4	AW18	
4	VCCO_4	AR18	
4	VCCO_4	AJ18	
4	VCCO_4	AH18	
4	VCCO_4	AJ17	
4	VCCO_4	AW14	
4	VCCO_4	AR14	
4	VCCO_4	AL13	
4	VCCO_4	AW10	
3	VCCO_3	AG15	
3	VCCO_3	AF15	
3	VCCO_3	AE15	
3	VCCO_3	AD15	
3	VCCO_3	AC15	
3	VCCO_3	AB15	
3	VCCO_3	AH14	
3	VCCO_3	AG14	